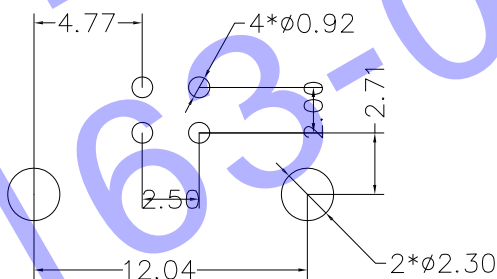
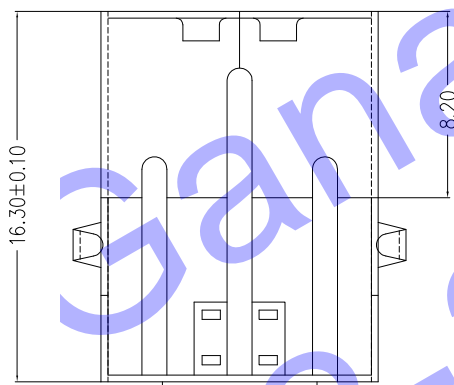
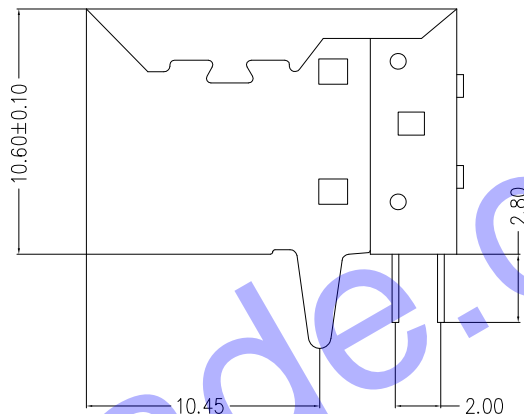
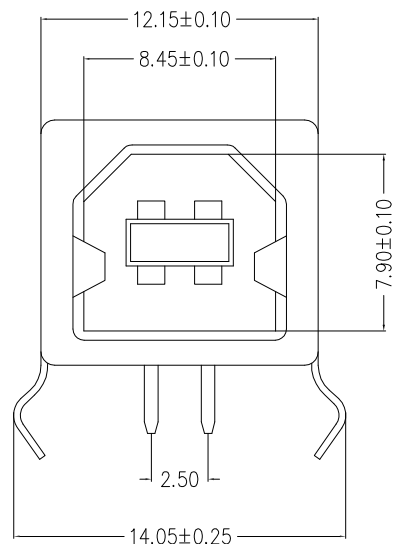


HSF



PCB.LaYOUT

特性:Specifications:

电器:Electrical:

接触阻抗:Contact Resistance

30 milliohms MAX

耐电压:Dielectric Withstanding Voltage:

500 V AC AT Sea Level

绝缘阻抗:Insulation Resistance:

100 MEGA ohms MIN

材料:Material:

塑胶:PBT

端子:Contact:Copper Alloy C2680H

铜壳/铁壳:Shell: Copper Alloy C2680H/Spcc

电镀:Finish:

端子:Contact: Plated Gold in Mating Area;

Tin/ On Solder Tails

接触点镀金.脚镀锡

铜壳/铁壳:Shell:

Nickel Plating

镀镍

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW JYHuang	DATE 2012/11/23	SCALE	FIT	PART NO. USB
				x.X	±0.40					
A1	12/11/23	MODIFY THE NOTES: 800mΩ min→800MΩ min	—	x.XX	±0.25	CHECK	DATE	UNIT	mm inch	CUSTOMER NO.
A0	12/06/25	NEW	—	x.XXX	±0.15	APPROVE	DATE	SIZE	A4	TITLE: GUSB-Z6178
				Angle	± 3°			SHEET	1/1	Customer NO.
				DIM	TOL			PROJ.		

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